

**AMENDMENTS TO THE ABSTRACT:**

Please replace the Abstract originally appearing on page 19 of the application with the following rewritten paragraph:

**ABSTRACT OF THE DISCLOSURE**

*ok*  
*NT*  
*12/26/64*  
~~Apparatus and methods~~ <sup>System</sup> ~~Methods~~ for placing conductive spheres on prefluxed bond pads of a substrate using a stencil plate with a pattern of through-holes positioned over the bond pads. Conductive spheres are placed in the through-holes by a moving feed mechanism and the spheres drop through the through-holes onto the bond pads. In one embodiment, the feed mechanism is a sphere hopper which crosses the entire through-hole pattern. In another embodiment, a shuttle plate fed spheres from a reservoir and reversibly moves about one-half of the pitch, moving from a non-discharge position to a discharge position.